

μ**PC3250T7L**

SiGe CMOS/BiCMOS Integrated Circuit IF Down-converter MMIC for Ku-band LNB Converter R09DS0052EJ0100 Rev.1.00 Oct 23, 2012

DESCRIPTION

The μ PC3250T7L is a CMOS/BiCMOS MMIC for Ku-band LNB converter.

This device is housed in a 24-pin plastic QFN (Quad Flat Non-Leaded) (T7L) package.

FEATURES

- Low power consumption : 3.3 V/63 mA, 208 mW
- Switched LO frequency : 9.75 G Hz, 10.6 GHz, 10.75 GHz
- 2 step Gain selected function : 41 dB/36 dB
- Low noise figure : 7.5 dB
- Fully integrated Mixer/Oscillator/PLL synthesizer/IF Amplifier/4-channel FET bias supply circuit/ Polarity control voltage detector/Tone control signal detector
- Integrated power save detector
- 24-pin plastic QFN (T7L) package $(4.0 \times 4.0 \times 0.6 \text{ mm})$

APPLICATIONS

• Ku-band Low Noise Block (LNB) converters for satellite receiver (DVB-S, ABS-S application)

ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Supplying Form
μPC3250T7L-E1	μPC3250T7L-E1-A	24-pin plastic QFN	C3250	 Embossed tape 12 mm wide
		(0.5 mm pitch)		• Pin 7 to 12 face the perforation side of the tape
		(Pb-Free)		Qty 5 kpcs/reel
				 Dry packing specification (MSL 3 Equivalent)

Remark To order evaluation samples, please contact your nearby sales office. Part number for sample order: *µ*PC3250T7L

CAUTION

Observe precautions when handling because these devices are sensitive to electrostatic discharge.



PIN CONNECTIONS



Pin No.	Pin Name						
1	NC	7	V _{DV}	13	Gsw	19	V _{DDPLL}
2	RF _{in}	8	V_{GV}	14	CVNeg	20	TonePol
3	NC	9	V _D 1	15	XO2	21	IF _{out}
4	R _{cal}	10	V _G 1	16	XO1	22	V _{CCIF}
5	V _{DH}	11	V _D 2	17	V _{ref}	23	V _{CCRF}
6	V_{GH}	12	V _G 2	18	CPout	24	LO _{sel}

Remark NC means no connection pin.

Heat sink of bottom side of this device is connected to GND.

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Ratings	Unit
Supply Voltage	V _{CCRF} , V _{CCIF} , V _{DDPLL}	+4.0	V
Control Voltage	VPOLA, VLOsel, GSW	+4.0	V
(TonePol, LO _{sel} , G _{SW})			
Power dissipation ^{Note}	P _{tot}	1.53	mW
Storage Temperature	T _{stg}	–55 to +125	°C
Operating Ambient Temperature	T _A	-40 to +85	°C
Input Power	P _{in}	0	dBm

Note: Mounted on double-sided copper-clad 50 \times 50 \times 0.51 mm laminated PWB, T_A = +85 ^ C



BLOCK DIAGRAM



Pin No.	Name	Description
1	NC	No Connection
2	RF in	Ku band RF signal input, AC coupling required.
3	NC	No Connection
4	R _{cal}	LNFET drain current adjust by resister
5	V_{DH}	Horizontal LNFET drain voltage supply
6	V _{GH}	Horizontal LNFET gate bias voltage
7	V _{DV}	Vertical LNFET drain voltage supply
8	V _{GV}	Vertical LNFET gate bias voltage
9	V _D 1	Common LNFET drain voltage supply 1
10	V _G 1	Common LNFET gate bias voltage 1
11	V _D 2	Common LNFET drain voltage supply 2
12	V _G 2	Common LNFET gate bias voltage 2
13	G _{SW}	Gain control input terminal
14	CVNeg	Negative voltage line decoupling
15	XO2	Crystal oscillator connection terminal 2
16	XO1	Crystal oscillator connection terminal 1
17	V _{ref}	Reference voltage line decoupling
18	CP _{out}	Charge pump output, connect capacitor for loop filter
19	V _{DDPLL}	PLL Power supply terminal. Decoupling capacitor required
20	TonePol	Tone and Polarity control signal input terminal
21	IF _{out}	L band IF signal output, AC coupling required
22	V _{CCIF}	IF Power supply terminal. Decoupling capacitor required
23	V _{CCRF}	RF Power supply terminal. Decoupling capacitor required
24	LO _{sel}	Local Oscillator frequency control input terminal

Remark NC means no connection pin.

Heat sink of bottom side of this device is connected to GND.



RECOMMENDED OPERATING RANGE (T_A = +25°C, unless otherwise specified)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage	V _{CCRF} , V _{CCIF} , V _{DDPLL}	+3.0	+3.3	+3.6	V
High level of Control Voltage (LO _{sel} , G _{SW})	V_High	$V_{DD}-0.5$	_	V _{DD} ^{Note 1}	V
Low level of Control Voltage (LO _{sel} , G _{SW})	V_Low	0	_	0.5	V
Operating Ambient Temperature	T _A	-40	+25	+85	°C
RF Input frequency	f _{RF}	10.7	-	12.75	GHz
IF Output frequency	f _{IF}	950	_	2 150	GHz
LO frequency	f _{LO}	-	9.75	_	GHz
		-	10.6	-	
		_	10.75	-0	
TONE control signal frequency	f _{TONE}	18	22	26	kHz
TONE control signal voltage	V _{TONE}	0.4	0.6	0.8	V р-р
Polarity control voltage ^{Note 2}	V _{POLA}	13		18	V
Input Voltage of pin 20 (TonePol)	V _{TP}	0		V _{DD}	V
Adjustment supply current for each FET	ID	5	10	18	mA

Notes: 1 V_{DD} : Supply Voltage = $V_{CCRF} = V_{CCIF} = V_{DDPLL}$

2 See the evaluation (application) circuit.

The detail connection of pin 20 (TonePol) is shown in the evaluation circuit.

This pin cannot be directly connected to 13 V/18 V polarity control voltage.

The polarity control voltage must be divided to a low voltage by the external resistors.

ELECTRICAL CHARACTERISTICS

 $(T_A = +25^{\circ}C, V_{CCRF} = V_{CCIF} = V_{DDPLL} = +3.3 V, Z_S = Z_L = 50 \Omega, f_{xtal} = 25 MHz, unless otherwise specified)$

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Total Supply Current 1 ^{Note}	I _{cc} 1	V _{POLA} > 7.0 V , Non-RF input,	50	63	80	mA
(V _{CCRF} , V _{CCIF} , V _{DDPLL})		G _{SW} = +3.3 V				
Normal mode		(without FETs bias supply current)				
(High Gain selected)						
Total Supply Current 2 ^{Note}	I _{cc} 2	V _{POLA} > 7.0 V , Non-RF input,	48.5	61.5	78.5	mA
(V _{CCRF} , V _{CCIF} , V _{DDPLL})		Gsw = 0 V				
Normal mode		(without FETs bias supply current)				
(Low Gain selected)						
Total Supply Current 3 ^{Note}	Icc3	$V_{POLA} = 0 V (< 3.6V)$	_	5	10	mA
(V _{CCRF} , V _{CCIF} , V _{DDPLL})		Non-RF input				
Power Save mode		(without FETs bias supply current)				

Note: See the evaluation (application) circuit.

The detail connection of pin 20 (TonePol) is shown in the evaluation circuit.

This pin cannot be directly connected to 13 V/18 V polarity control voltage.

The polarity control voltage must be divided to a low voltage by the external resistors.



ELECTRICAL CHARACTERISTICS

(T_A = +25°C, V_{CCRF} = V_{CCIF} = V_{DDPLL} = +3.3 V, G_{SW} = +3.3 V, Z_S = Z_L = 50 Ω , f_{xtal} = 25 MHz, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Conversion Gain 1 ^{Note 1}	G _{conv} 1	$\label{eq:flow} \begin{array}{l} f_{LO}=9.75~GHz, \ f_{IF}=1.5~GHz, \\ P_{in}=-50~dBm \end{array}$	37	41	45	dB
Conversion Gain 2 ^{Note 1}	G _{conv} 2	$\label{eq:LO} \begin{array}{l} f_{LO} = 10.6 \text{ GHz}, \ f_{IF} = 1.5 \text{ GHz}, \\ P_{in} = -50 \text{ dBm} \end{array}$	37	41	45	dB
Conversion Gain 3 ^{Note 1}	G _{conv} 3	$\label{eq:LO} \begin{array}{l} f_{LO} = 10.75 \text{ GHz}, \ f_{IF} = 1.5 \text{ GHz}, \\ P_{in} = -50 \text{ dBm} \end{array}$	37	41	45	dB
POLA control Threshold Voltage 1 ^{Note 1}	$V_{th_POLA}1$	Power Save mode to Normal mode Dividing resistor : 8.2 k Ω /51 k Ω	3.6	_	7.0	V
POLA control Threshold Voltage 2 ^{Note 1} (Channel selection)	$V_{th_POLA}2$	Vertical mode to Horizontal mode Dividing resistor : 8.2 k Ω /51 k Ω	15.2	15.7	16.2	V
TONE control signal Threshold Voltage ^{Note 1} (Channel selection)	V _{th_TONE}	Low band to High band $f_{TONE} = 22 \text{ kHz}$, Duty Cycle = 50%, Pulse wave Divider capacitor : 0.1 $\nu E/0.1 \nu E$	0.1	0.15	0.35	V _{p-p}
Drain Voltage H ^{Note 1, 2}	V _{DH}	$V_{POLA} = 18 \text{ V}, I_D = 10 \text{ mA},$ $R_{cal} = 22 \text{ k}\Omega$	1.8	2.0	2.2	V
Drain Voltage V ^{Note 1, 2}	V _{DV}	$V_{POLA} = 13 \text{ V}, \text{ I}_{D} = 10 \text{ mA},$ $R_{cal} = 22 \text{ k}\Omega$	1.8	2.0	2.2	V
Drain Voltage 1 ^{Note 1, 2}	V _D 1	$I_D = 10 \text{ mA}, \text{ R}_{cal} = 22 \text{ k}\Omega$	1.8	2.0	2.2	V
Drain Voltage 2 ^{Note 1, 2}	V _D 2	$I_D = 10 \text{ mA}, R_{cal} = 22 \text{ k}\Omega$	1.8	2.0	2.2	V
Drain Current H ^{Note 1, 2}	I _{DH}	$V_{POLA} = 18 V, R_{cal} = 22 k\Omega$	8.5	10	11.5	mA
Drain Current V ^{Note 1, 2}	I _{DV}	$V_{POLA} = 13 \text{ V}, \text{ R}_{cal} = 22 \text{ k}\Omega$	8.5	10	11.5	mA
Drain Current 1 ^{Note 1, 2}	I _D 1	$R_{cal} = 22 \ k\Omega$	8.5	10	11.5	mA
Drain Current 2 ^{Note 1, 2}	I _D 2	$R_{cal} = 22 \ k\Omega$	8.5	10	11.5	mA
Gate Voltage H ^{Note 1, 2} of FET OFF mode	V _{GH}	V _{POLA} = 13 V	-2.0	-2.5	-3.0	V
Gate Voltage V ^{Note 1, 2} of FET OFF mode	V _{GV}	V _{POLA} = 18 V	-2.0	-2.5	-3.0	V

Notes: 1 See the evaluation (application) circuit.

The detail connection of pin 20 (TonePol) is shown in the evaluation circuit.

This pin cannot be directly connected to 13 V/18 V polarity control voltage.

The polarity control voltage must be divided to a low voltage by the external resistors.

2 See the graph of "R_{cal} vs. I_{DFET}, V_{DFET}." FET's drain current can be adjusted by the external resisters (R_{cal}).



STANDARD CHARACTERISTICS FOR REFERENCE

(T_A = +25°C, V_{CCRF} = V_{CCIF} = V_{DDPLL} = +3.3 V, G_{SW} = +3.3V, Z_S = Z_L = 50 Ω , f_{xtal} = 25 MHz, unless otherwise specified)

Parameter	Symbol	Test Conditions	Reference Value	Unit
Conversion Gain Flatness 1	ΔG_{conv} 1	$f_{LO} = 9.75 \text{ GHz}, f_{IF} = 0.95 \text{ G to } 1.95 \text{ GHz}, P_{in} = -50 \text{ dBm}$	2.5	dB
Conversion Gain Flatness 2	$\Delta G_{conv} 2$	f_{LO} = 10.6 GHz, f_{IF} = 1.1 G to 2.15 GHz, P_{in} = –50 dBm	2.0	dB
Conversion Gain Flatness 3	$\Delta G_{conv}3$	f_{LO} = 10.75 GHz, f_{IF} = 0.95 G to 2.0 GHz, P_{in} = –50 dBm	2.0	dB
Noise Figure 1	NF1	f_{LO} = 9.75 GHz, f_{IF} = 1.5 GHz	7.5	dB
Noise Figure 2	NF2	$f_{LO} = 10.6 \text{ GHz}, f_{IF} = 1.5 \text{ GHz}$	7.5	dB
Noise Figure 3	NF3	$f_{LO} = 10.75 \text{ GHz}, f_{IF} = 1.5 \text{ GHz}$	7.5	dB
Gain 1 dB Compression Output Power 1	P _{O(1 dB)} 1	f _{LO} = 9.75 GHz, f _{IF} = 1.5 GHz	5	dBm
Gain 1 dB Compression Output Power 2	P _{O (1 dB)} 2	$f_{LO} = 10.6 \text{ GHz}, f_{IF} = 1.5 \text{ GHz}$	5	dBm
Gain 1 dB Compression Output Power 3	P _{O(1 dB)} 3	$f_{LO} = 10.75 \text{ GHz}, f_{IF} = 1.5 \text{ GHz}$	5	dBm
Output 3rd Order Intercept Point 1	OIP ₃ 1	$f_{LO} = 9.75 \text{ GHz},$ $f_{IF}1 = 1500 \text{ MHz}, f_{IF}2 = 1501 \text{ MHz}$	16	dBm
Output 3rd Order Intercept Point 2	Output 3rd Order Intercept Point 2 OIP ₃ 2 $f_{LO} = 10.6 \text{ GHz},$ $f_{IF1} = 1500 \text{ MHz}, f_{IF2} = 1501 \text{ MHz}$		16	dBm
Output 3rd Order Intercept Point 3	OIP ₃ 3	f _{LO} = 10.75 GHz, f _{IF} 1 = 1 500 MHz, f _{IF} 2 = 1 501 MHz	16	dBm
RF Input Return Loss	RL _{RF}	f _{RF} = 10.7 G to 12.75 GHz	10	dB
IF Output Return Loss	RLIF	f _{RF} = 950 M to 2 150 MHz	10	dB
Phase Noise 1	PN1	1 kHz offset	-78	dBc/Hz
Phase Noise 2	PN2	10 kHz offset	-80	dBc/Hz
Phase Noise 3	PN3	100 kHz offset	-88	dBc/Hz
Phase Noise 4	PN4	1 MHz offset	-108	dBc/Hz
Integrated phase noise density	Φnλ (itg)	Integrated offset frequency 10 k to 15 MHz	1.7	°RMS
Local signal Leakage 1	L _{o_Leakage} 1	$f_{LO} = 9.75 \text{ GHz}$, Local to RF_{in}	-58	dBm
Local signal Leakage 2	$L_{o_Leakage}2$	f_{LO} = 10.6 GHz, Local to RF _{in}	-58	dBm
Local signal Leakage 3	L _{o_Leakage} 3	$f_{LO} = 10.75GHz$, Local to RF_{in}	-57	dBm
Total Circuit current 1 (Reference status 1)	I _{CC} 1	2ch FET bias supplied V _{POLA} > 7.0 V, Non-RF	83	mA
Total Circuit current 2 (Reference status 2)	I _{CC} 2	3ch FET bias supplied V _{POLA} > 7.0 V, Non-RF	93	mA

Note: See the evaluation (application) circuit.



STANDARD CHARACTERISTICS FOR REFERENCE

(T_A = +25°C, V_{CCRF} = V_{CCIF} = V_{DDPL}L = +3.3 V, G_{SW} = 0 V, Z_S = Z_L = 50 Ω , f_{xtal} = 25 MHz, unless otherwise specified)

Parameter	Symbol	Test Conditions	Reference Value	Unit
Conversion Gain 1	G _{conv} 1	$\label{eq:Logitarian} \begin{split} f_{LO} &= 9.75 \text{ GHz}, \ f_{IF} = 1.5 \text{ GHz}, \\ P_{in} &= -50 \text{ dBm} \end{split}$	36	dB
Conversion Gain 2	G _{conv} 2	$\label{eq:LO} \begin{array}{l} f_{LO} = 10.6 \text{ GHz}, \ f_{IF} = 1.5 \text{ GHz}, \\ P_{in} = -50 \text{ dBm} \end{array}$	36	dB
Conversion Gain 3	G _{conv} 3	$\label{eq:LO} \begin{array}{l} f_{LO} = 10.75GHz, f_{IF} = 1.5 \ GHz, \\ P_{in} = -50 \ dBm \end{array}$	36	dB
Conversion Gain Flatness 1	ΔG_{conv} 1	f_{LO} = 9.75 GHz, $f_{\rm IF}$ = 0.95 G to 1.95 GHz, $P_{\rm in}$ = –50 dBm	2.5	dB
Conversion Gain Flatness 2	$\Delta G_{conv} 2$	f_{LO} = 10.6 GHz, f_{IF} = 1.1 G to 2.15 GHz, P_{in} = –50 dBm	2.0	dB
Conversion Gain Flatness 3	$\Delta G_{conv}3$	$f_{LO} = 10.75 \text{ GHz}, f_{IF} = 0.95 \text{ G to } 2.0 \text{ GHz},$ $P_{in} = -50 \text{ dBm}$	2.0	dB
Noise Figure 1	NF1	f _{LO} = 9.75 GHz, f _{IF} = 1.5 GHz	7.5	dB
Noise Figure 2	NF2	f _{LO} = 10.6 GHz, f _{IF} = 1.5 GHz	7.5	dB
Noise Figure 3	NF3	f _{LO} = 10.75 GHz, f _{IF} = 1.5 GHz	7.5	dB
Gain 1 dB Compression Output Power 1	P _{O(1 dB)} 1	f _{LO} = 9.75 GHz, f _{IF} = 1.5 GHz	2	dBm
Gain 1 dB Compression Output Power 2	$P_{O(1\;dB)}2$	f _{LO} = 10.6 GHz, f _{IF} = 1.5 GHz	2	dBm
Gain 1 dB Compression Output Power 3	P _{O(1 dB)} 3	$f_{LO} = 10.75 \text{ GHz}, f_{IF} = 1.5 \text{ GHz}$	2	dBm
Output 3rd Order Intercept Point 1	OIP ₃ 1	f _{LO} = 9.75 GHz, f _{IF} 1 = 1 500 MHz, f _{IF} 2 = 1 501 MHz	12	dBm
Output 3rd Order Intercept Point 2	OIP ₃ 2	$f_{LO} = 10.6 \text{ GHz}, f_{IF}1 = 1 500 \text{ MHz},$ $f_{IF}2 = 1 501 \text{ MHz}$	12	dBm
Output 3rd Order Intercept Point 3	OIP ₃ 3	f _{LO} = 10.75 GHz, f _{IF} 1 = 1 500 MHz, f _{IF} 2 = 1 501 MHz	12	dBm
RF Input Return Loss	RL _{RF}	f _{RF} = 10.7 G to 12.75 GHz	10	dB
IF Output Return Loss	RLIF	f _{RF} = 950 M to 2 150 MHz	10	dB

Note: See the evaluation (application) circuit.



TRUTH TABLE

Local Oscillator frequency select pin function description (pin 24 (LO_{sel}))

LO _{sel}	LO _{sel} (DVB-S	LO _{sel} = High (ABS-S mode)	
	Tone signal = 0 kHz	Tone signal = 22 kHz	-
Local Oscillator frequency	9.75 GHz	10.6 GHz	10.75 GHz

Note: The relationships between the LO_{sel} state and the pin connection are as follows.

By connecting this pin to GND line (0 V DC), LOsel becomes "Low" state.

By connecting this pin to V_{DD} line (V_{DD} DC), LO_{sel} becomes "High" state.

The V_{DD} described above means the power supply voltage. Its value is 3.3 V the same as $V_{\text{CCRF}},\,V_{\text{CCIF}}$, and V_{DDPLL} .

FET's DC bias control pin function description (pin 20 (TonePol), polarity control voltage)

	FETs	Horizont	al FET	Vertica	al FET	Commor	Common FET 1		Common FET 2	
V _{POLA}		V _{GH}	V _{DH}	V _{GV}	V _{DV}	V _G 1	V _D 1	V _G 2	V _D 2	
Normal	V _{POLA}	Controlled	Controlled	Disable	Disable	Controlled	Controlled	Controlled	Controlled	
mode	> 16.2 V Note	(-2.5 V to +1 V)	(≈ 2 V)	(–2.5V)	(0 V)	(-2.5 V to +1 V)	(≈ 2 V)	(-2.5 V to +1 V)	(≈ 2 V)	
	V _{POLA}	Disable	Disable	Controlled	Controlled	Controlled	Controlled	Controlled	Controlled	
	< 15.2 V Note	(–2.5 V)	(0 V)	(-2.5 V to +1 V)	(≈ 2 V)	(-2.5 V to +1 V)	(≈ 2 V)	(-2.5 V to +1 V)	(≈ 2 V)	
Power	V _{POLA}	Disable	Disable	Controlled	Controlled	Controlled	Controlled	Controlled	Controlled	
Save mode	< 3.6 V Note	(–2.5 V)	(0 V)	(-2.5 V to +1 V)	(≈ 2 V)	(-2.5 V to +1 V)	(≈ 2 V)	(-2.5 V to +1 V)	(≈ 2 V)	

Note: Dividing Resistor: 8.2 k Ω /51 k Ω

See the evaluation (application) circuit.

The detail connection of pin 20 (TonePol) is shown in the evaluation circuit. This pin cannot be directly connected to 13 V/18 V polarity control voltage. The polarity control voltage must be divided to a low voltage.

20









Remark The graphs indicate nominal characteristics.







EVALUATION CIRCUIT





APPLICATION CIRCUIT

FOR SINGLE LNB (REFERENCE ONLY)





FOR TWIN LNB (DOUBLE SINGLE LNB) (REFERENCE ONLY)





MOUNTING PAD LAYOUT DIMENSIONS

24-PIN PLASTIC QFN (T7L) PACKAGE (4.0 × 4.0 × 0.6 mm) (UNIT : mm)





PACKAGE DIMENSIONS

24-PIN PLASTIC QFN (T7L) PACKAGE (4.0 × 4.0 × 0.6 mm) (UNIT : mm)





RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions		Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) Time at peak temperature Time at temperature of 220°C or higher	: 260°C or below : 10 seconds or less : 60 seconds or less : 120+20 seconds	IR260
	Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 3 times : 0.2% (Wt.) or below	
Partial Heating	Peak temperature (package surface temperature) Soldering time (per side of device) Maximum chlorine content of rosin flux (% mass)	: 350°C or below : 3 seconds or less : 0.2% (Wt.) or below	HS350

CAUTION

Do not use different soldering methods together (except for partial heating).



Revision	History
1.0010101	

		Description	
Rev.	Date	Page	Summary
1.00	Oct 23, 2012	-	First edition issued



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California Eastern Laboratories, Inc. 4590 Patrick Henry Drive, Santa Clara, California 95054, U.S.A. Tel: +1408-989-0207, Fax: +1408-988-0279 Renesas Electronics Europe Limited Dukes Meadow, Millboard Road, Boume End, Buckinghamshire, SL8 5FH, U.K Tel: +44-1628-651-700, Fax: +44-1628-651-804 Renesas Electronics Europe GmbH Arcadiastrasse 10, 40472 Düsseldorf, Germany Tel: +49-211-65030, Fax: +49-211-6503-1327 Renesas Electronics (China) Co., Ltd. Th Floor, Quantum Plaza, No.27 ZhiChunLu Haidian District, Beijing 100083, P.R.China Tel: +86-10-8235-1155, Fax: +86-10-8235-7679 Renesas Electronics (Anghal) Co., Ltd. Unit 204, 205, AZIA Center, No.1233 Lujiazui Ring Rd., Pudong District, Shanghai 200120, China Tel: +86-21-8877-1818, Fax: +86-21-6887-7858 Renesas Electronics Taing Fax: +86-21-6887-7858 Renesas Electronics Taing, Fax: +86-202-9044 Unit 1801-1613, 16F-, Tower 2, Grand Century Place, 193 Prince Edward Road West, Mongkok, Kowloon, Hong Kong Tel: +852-2868-9318, Fax: +852 2886-9229044 Renesas Electronics Injapie, Taiwan Tel: +86-2-8175-9600, Fax: +886-28175-9670 Renesas Electronics Singapore Pte. Ltd. 80 Bendemeer Road, Unit 960-02 Hylitu Kinnovation Centre Singapore 339949 Tel: +55-213-0200, Fax: +60-3-7955-9610 Renesas Electronics Korea Dn, Amorp Trade Centre, No. 18, Jin Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia Tel: +80-2-859-3930, Fax: +80-2-810-9510 Renesas Electronics Korea Co., Ltd. 11F., Samik Lavied or Bidg, 720-2 Yeoksam-Dong, Kangnam-Ku, Seoul 135-080, Korea Tel: +80-2-859-3737, Fax: +82-2-5514